

**In the Claims:**

1. (Currently Amended) A testing method for testing electrical coupling between a semiconductor device and a test carrier, comprising:

loading the test carrier onto a carrier socket;

loading the test carrier with the semiconductor device such that contacts of the semiconductor device directly contact corresponding contacts of the test carrier,

wherein the electrical coupling between the test carrier and the semiconductor device is tested immediately after the loading of the test carrier with the semiconductor device ~~[[; and]]~~ ,

wherein the semiconductor device comprises one or more exclusive test contacts for testing the electrical coupling between the semiconductor device and the test carrier; and

unloading the semiconductor device from the test carrier based on a criterion, wherein the criterion is based on the electrical coupling between the test carrier and the semiconductor device obtained from the test.

2. (Currently Amended) The testing method according to claim 1, further comprising connecting the test carrier to a testing apparatus.

3. (Currently Amended) The testing method according to claim 2, wherein the carrier is connected to the testing apparatus, ~~and the carrier is subsequently loaded~~ after loading the test carrier with the semiconductor device.

4. (Currently Amended) The testing method according to claim 1, wherein the test carrier is loaded at a carrier loading station, and the electrical coupling between the test carrier and the semiconductor device is tested before the test carrier is transported to a further testing station.

5. (Currently Amended) The testing method according to claim 2, wherein the electrical coupling between the test carrier and the semiconductor device is tested by the testing apparatus.
6. (Currently Amended) The testing method according to claim 5, wherein the testing apparatus is configured such that it tests the electrical coupling between the test carrier and the semiconductor device, but not functioning of the semiconductor device.
7. (Currently Amended) The testing method according to claim 1, wherein the electrical coupling between the test carrier and the semiconductor device is tested less than 2 seconds after loading [[of]] the test carrier with the semiconductor device.
8. (Currently Amended) The testing method according to claim 1, further comprising determining during the testing of the electrical coupling between the test carrier and the semiconductor device whether an electrical contact has been established between a test contact of the semiconductor device and an assigned pad of the test carrier after loading [[of]] the test carrier with the semiconductor device.
9. (Currently Amended) The testing method according to claim 1, further comprising determining during the testing of the electrical coupling between the test carrier and the semiconductor device whether a respective electrical contact has been established between a plurality of test contacts of the semiconductor device and respectively assigned pads of the test carrier after loading [[of]] the test carrier with the semiconductor device.
10. (Currently Amended) The testing method according to claim 8, wherein power of current flowing through the test contact of the semiconductor device is determined to find whether

electrical contact has been established between the test contact of the semiconductor device and the assigned pad of the test carrier.

11. (Currently Amended) The testing method according to claim 8, wherein an amount of voltage dropping across the corresponding semiconductor device contact is determined to find whether electrical contact has been established between the test contact of the semiconductor device and the assigned pad of the test carrier.

12-14. (Canceled)

15. (Currently Amended) The testing method according to claim 1, wherein the one or more exclusive test contacts are not used during ordinary operation of the semiconductor device.

16. (Currently Amended) The testing method according to claim 1, wherein the semiconductor device further comprises at least one additional contact used during ordinary operation of the semiconductor device but not during testing.

17. (Currently Amended) The testing method according to claim 1, wherein the one or more exclusive test contacts are not used for testing [[the]] functioning of the semiconductor device.

18. (Currently Amended) The testing method according to claim 17, wherein the semiconductor device further comprises at least one additional contact used for testing the functioning of the semiconductor device.

19-22. (Canceled)

23. (Previously Presented) The testing method according to claim 1, wherein the one or more exclusive test contacts are provided on a bottom of the semiconductor device.

24. (Canceled)

25. (Previously Presented) The testing method according to claim 1, wherein the test carrier is a TSOP test carrier.

26-29. (Canceled)

30. (Currently Amended) A testing system for testing a semiconductor device comprising:  
a carrier for transporting the semiconductor device;

a loader to load the semiconductor device adjacent the carrier, wherein the loading forms an electrical contact between the semiconductor device and the carrier;

a contact tester electrically contacting the carrier, wherein the contact tester tests electrical coupling of the semiconductor device with the carrier, wherein the test determines good or defective electrical contacts between the semiconductor device and the carrier; [[and]]

a functional tester physically separated from the contact tester, wherein the functional tester tests an electrical functionality of semiconductor devices with good electrical contacts between the semiconductor device and the carrier; and

a carrier socket for holding the carrier, the carrier socket being coupled to the contact tester, wherein the carrier is coupled to the contact tester through the carrier socket.

31. (Previously Presented) The testing system of claim 30, wherein the loader unloads semiconductor devices with defective contacts.

32. (Previously Presented) The testing system of claim 30, wherein the functional tester uses a “burn-in” test to test the electrical functionality of the semiconductor device.

33. (Previously Presented) The testing system of claim 30, wherein the semiconductor device electrically couples to the carrier by directly contacting semiconductor device contacts with corresponding contacts on the carrier.

34. (Canceled)

35. (Currently Amended) A testing system that sequentially tests semiconductor devices, wherein a test is performed on each semiconductor device by the testing system, and wherein each test comprises:

loading a carrier inside a carrier socket;

loading the semiconductor device inside [[a]] the carrier;

measuring electrical connectivity of electrical connections between the semiconductor device and the carrier;

identifying semiconductor devices with defective electrical connections between the semiconductor device and the carrier based on the measurement; and

unloading semiconductor devices with defective electrical connections between the semiconductor device and the carrier from the carrier.

36. (Previously Presented) The testing system of claim 35, wherein the semiconductor device comprises additional contacts used only by the testing system.

37. (Currently Amended) The testing system of claim 35, wherein the semiconductor device without defective connections is passed onto a functional tester, wherein the functional tester tests [[the]] electrical functionality of the semiconductor device.

38. (Previously Presented) The testing system of claim 37, wherein the functional tester uses a “burn-in” test to test the electrical functionality of the semiconductor device.

39. (Currently Amended) The testing system of claim 35, wherein the testing system does not test [[the]] electrical functionality of the semiconductor device.